



# HYSOL<sup>®</sup> ES1301<sup>™</sup>

April 2008

## PRODUCT DESCRIPTION

HYSOL<sup>®</sup> ES1301<sup>™</sup> provides the following product characteristics:

<b>Technology</b>	Epoxy
Appearance (Part A)	Black
Appearance (Part B)	Amber
Appearance (cured)	Black
Components	Two component - requires mixing
Mix Ratio, by volume - Part A: Part B	2 : 1
Mix Ratio, by weight - Part A: Part B	100 : 38
<b>Cure</b>	Heat cure
<b>Application</b>	Potting and Encapsulating

HYSOL<sup>®</sup> ES1301<sup>™</sup> is a silica filled epoxy casting system recommended for coils, transformers, and general purpose casting.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

### Part A Properties

Filler Content, %	50
Viscosity, Brookfield - RVF, 25 °C, cP: Spindle 5, speed 20 rpm	10,500
Density, @ 25 °C, g/cm <sup>3</sup>	1.6

### Part B Properties

Filler Content, %	0
Viscosity, Brookfield - RVF, 25 °C, cP: Spindle 5, speed 20 rpm	750
Density, @ 25 °C, g/cm <sup>3</sup>	1.19

### Mixed Properties

Viscosity, Brookfield - RVF, 25 °C, cP: Spindle 3, speed 20 rpm	1,600
Gel Time, 200gm mass @ 25 °C, hours	>8

## TYPICAL CURING PERFORMANCE

### Recommended Curing Conditions

4 hours @ 110 °C (Recommended cure)
2 hours @ 125 °C (Alternate cure)

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties:

Glass Transition Temperature (Tg), °C	112
Coefficient of Linear Thermal Expansion, ppm/°C:	
Alpha 1, Above Tg @ 130 to 150 °C	169
Alpha 2, Below Tg @ 40 to 60 °C	67
Thermal Conductivity, W/mk	0.42
Density, , g/cm <sup>3</sup>	1.44
Linear Shrinkage, %	0.84
Shore Hardness, Durometer D	90 to 95
Tensile Strength, psi	6,953
Flexural Strength, psi	15,786
Tensile Elongation, %	1.0

### Electrical Properties:

Dielectric Strength, 10 mils thickness, volts/mil	1,096
Breakdown voltage, (kV), @ 25 °C	21.8
Arc Resistance, seconds	139
Volume Resistivity, ohm/cm @ 25°C	1.9×10 <sup>16</sup>
Surface Resistivity, ohms @ 25°C	1.22×10 <sup>16</sup>
Volume Resistivity, ohm/cm @ 105°C	1.42×10 <sup>14</sup>
Surface Resistivity, ohms @ 105°C	1.98×10 <sup>14</sup>
Dielectric Constant / Dissipation Factor @ 25°C:	
100 Hz	3.63 / 0.005
1 kHz	3.62 / 0.004
100 kHz	3.57 / 0.008
Dielectric Constant / Dissipation Factor @ 105°C:	
100 Hz	4.5 / 0.068
1 kHz	4.18 / 0.039
100 kHz	3.9 / 0.016

## GENERAL INFORMATION

**For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).**

### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Note: Before using this product please purge approximately 30 ml. of material prior to application. Discard purged material in accordance with the Material Safety Data Sheet. A video instruction is available upon request.

### Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: 20 °C to 30 °C. Storage below 20 °C or greater than 30 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

### Conversions

(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/mm x 5.71 = lb/in
N/mm <sup>2</sup> x 145 = psi
MPa x 145 = psi
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP



**Note**

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

**Trademark usage**

Except as otherwise noted, all trademarks in this document are trademarks of Henkel Corporation in the U.S. and elsewhere. ® denotes a trademark registered in the U.S. Patent and Trademark Office.

Reference 1.2